

AMENDMENTS TO THE CLAIMS:

Please cancel Claims 6 and 7 without prejudice to or disclaimer of the subject matter recited therein.

Please amend Claims 1, 5, and 9 through 16 as follows:

1. (Currently Amended) A solid state image pick-up device formed on a chip, comprising:
 - a pixel region;
 - horizontal scanning circuits arranged along sides of the chip sandwiching the pixel region for reading a signal charge from the pixel region;
 - a vertical scanning circuit arranged along a side of the chip not parallel to ~~the a~~ side of the chip ~~and~~ along which ~~none of the a~~ horizontal scanning ~~circuits circuit,~~ of the ~~horizontal scanning circuits,~~ is arranged, ~~and having wherein the vertical scanning circuit~~ ~~has~~ a lower driving frequency than that of the horizontal scanning circuits;
 - an amplifier for amplifying the signal charge read from the pixel region by the horizontal scanning circuits, outputting video signals; and
 - a pad for outputting the video signals to an outside of the chip, the pad being arranged along a side of the chip along which none of the horizontal scanning circuits and the vertical scanning circuit is arranged.
2. (Previously Presented) The solid state image pick-up device according to claim 1, wherein in the pixel region, pixels having an active element are two-dimensionally arranged.

3. (Previously Presented) The solid state image pick-up device according to claim 2, wherein the active element comprises at least one selected from the group consisting of a transfer MOS transistor, a reset MOS transistor, a source follower input MOS transistor, and a selection MOS transistor.

4. (Cancelled)

5. (Currently Amended) The solid state image pick-up device according to claim 2, wherein the pixel region is formed into a rectangle, and the ~~first horizontal shift register is scanning circuits are~~ arranged closer to a long side of the pixel region.

6 - 7. (Cancelled)

8. (Original) A camera, comprising:
the solid state image pick-up device according to claim 1;
a lens for forming an optical image of a subject; and
a signal processing unit for processing a signal from the solid state image pick-up device.

9. (Currently Amended) A solid state image pick-up device formed on a chip, comprising:

a pixel region;
horizontal scanning circuits arranged along sides of the chip sandwiching the pixel region for reading a signal charge from the pixel region;

a vertical scanning circuit arranged along a side of the chip not parallel to ~~the a~~
side of the chip ~~and~~ along which ~~none of the a~~ horizontal scanning ~~circuits circuit, of the~~
~~horizontal scanning circuits,~~ is arranged, ~~and having wherein the vertical scanning circuit~~
~~has~~ a lower driving frequency than that of the horizontal scanning circuits;

an amplifier for amplifying the signal charge read from the pixel region by the
horizontal scanning circuits, outputting video signals; and

a pad for supplying a voltage to the amplifier, the pad being arranged along a
side of the chip along which none of the horizontal scanning circuits and the vertical
scanning circuit is arranged.

10. (Currently Amended) A solid state image pick-up device formed on a
chip, comprising:

a pixel region;

horizontal scanning circuits arranged along sides of the chip sandwiching the
pixel region for reading a signal charge from the pixel region;

a vertical scanning circuit arranged along a side of the chip not parallel to ~~the a~~
side of the chip ~~and~~ along which ~~none of the a~~ horizontal scanning ~~circuits circuit, of the~~
~~horizontal scanning circuits,~~ is arranged, ~~and having wherein the vertical scanning circuit~~
~~has~~ a lower driving frequency than that of the horizontal scanning circuits;

an amplifier for amplifying the signal charge read from the pixel region by the
horizontal scanning circuits, outputting video signals; and

a pad for supplying a predetermined voltage or a ground voltage to an active
element included in a pixel in the pixel region, the pad being arranged along a side of the
chip along which none of the horizontal scanning circuits and the vertical scanning circuit
is arranged.

11. (Currently Amended) The solid state image pick-up device according to claim 1, wherein ~~the~~ side portions along which the ~~first and second horizontal shift registers scanning circuits~~ are arranged and a side portion along which the vertical scanning circuit is arranged are adjacent to each other.

12. (Currently Amended) The solid state image pick-up device according to claim 9, wherein ~~the~~ side portions along which the ~~first and second horizontal shift registers scanning circuits~~ are arranged and a side portion along which the vertical scanning circuit is arranged are adjacent to each other.

13. (Currently Amended) The solid state image pick-up device according to claim 10, wherein ~~the~~ side portions along which the ~~first and second horizontal shift registers scanning circuits~~ are arranged and a side portion along which the vertical scanning circuit is arranged are adjacent to each other.

14. (Currently Amended) The solid state image pick-up device according to claim 1, wherein the pad is arranged only along a side portion of the chip at an angle of 90 degrees to ~~the a~~ side portion along which ~~the first a horizontal shift register scanning circuit, of the horizontal scanning circuits,~~ is arranged.

15. (Currently Amended) The solid state image pick-up device according to claim 9, wherein the pad is arranged only along a side portion of the chip at an angle of 90 degrees to ~~the a~~ side portion along which ~~the first a horizontal shift register scanning circuit, of the horizontal scanning circuits,~~ is arranged.

16. (Currently Amended) The solid state image pick-up device according to claim 10, wherein the pad is arranged only along a side portion of the chip at an angle of 90 degrees to ~~the a~~ side portion along which ~~the first a horizontal shift register scanning circuit, of the horizontal scanning circuits,~~ is arranged.